## INTEGRATED CIRCUITS

## DATA SHEET

# **74LV10**Triple 3-input NAND gate

Product data Supersedes data of 1998 Apr 20





## **Triple 3-input NAND gate**

74LV10

#### **FEATURES**

- Optimized for Low Voltage applications: 1.0 V to 3.6 V
- $\bullet$  Accepts TTL input levels between  $V_{CC}$  = 2.7 V and  $V_{CC}$  = 3.6 V
- Typical  $V_{OLP}$  (output ground bounce) < 0.8 V at  $V_{CC}$  = 3.3 V,  $T_{amb} = 25 \, ^{\circ}C.$
- Typical V<sub>OHV</sub> (output V<sub>OH</sub> undershoot) > 2 V at V<sub>CC</sub> = 3.3 V,  $T_{amb} = 25 \, ^{\circ}C.$
- Output capability: standard
- I<sub>CC</sub> category: SSI

#### DESCRIPTION

The 74LV10 is a low-voltage Si-gate CMOS device and is pin and function compatible with 74HC/HCT10.

The 74LV10 provides the 3-input NAND function.

#### **QUICK REFERENCE DATA**

GND = 0 V;  $T_{amb}$  = 25 °C;  $t_r$  =  $t_f \le 2.5$  ns

| SYMBOL                             | PARAMETER                              | CONDITIONS   | TYPICAL | UNIT |
|------------------------------------|--|--|---------|------|
| t <sub>PHL</sub> /t <sub>PLH</sub> | Propagation delay nA, nB, nC to nY     | $C_L = 15 \text{ pF};$<br>$V_{CC} = 3.3 \text{ V}$ | 9       | ns   |
| C <sub>I</sub>                     | Input capacitance                      |  | 3.5     | pF   |
| C <sub>PD</sub>                    | Power dissipation capacitance per gate | See Notes 1 and 2                                  | 12      | pF   |

#### NOTES:

1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ )

 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma (C_L \times V_{CC}^2 \times f_o)$  where: N = number of outputs switching;

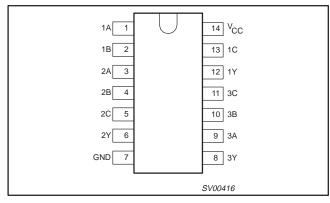
 $f_i$  = input frequency in MHz;  $C_L$  = output load capacitance in pF;  $f_o$  = output frequency in MHz;  $V_{CC}$  = supply voltage in V;

 $\Sigma$  (C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of the outputs. 2. The condition is V<sub>I</sub> = GND to V<sub>CC</sub>

#### ORDERING INFORMATION

| PACKAGES          | TEMPERATURE RANGE | ORDER CODE | PKG. DWG. # |
|-------------------|-------------------|------------|-------------|
| 14-Pin Plastic SO | –40 °C to +125 °C | 74LV10D    | SOT108-1    |

#### PIN CONFIGURATION



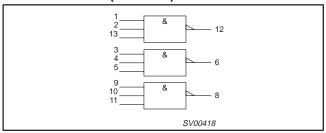
#### PIN DESCRIPTION

| PIN NUMBER | SYMBOL          | NAME AND FUNCTION       |
|------------|-----------------|-------------------------|
| 1, 3, 9    | 1A – 3A         | Data inputs             |
| 2, 4, 10   | 1B – 3B         | Data inputs             |
| 7          | GND             | Ground (0 V)            |
| 12, 6, 8   | 1Y – 3Y         | Data outputs            |
| 13, 5, 11  | 1C – 3C         | Data inputs             |
| 14         | V <sub>CC</sub> | Positive supply voltage |

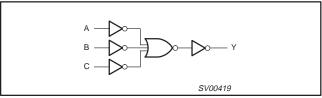
## Triple 3-input NAND gate

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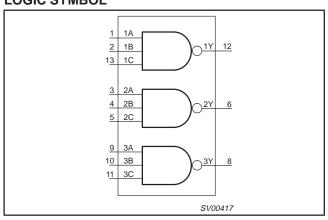
#### LOGIC SYMBOL (IEEE/IEC)



## LOGIC DIAGRAM (ONE GATE)



#### LOGIC SYMBOL



#### **FUNCTION TABLE**

|    | INPUTS |    | OUTPUTS |
|----|--------|----|---------|
| nA | nB     | nC | nY      |
| L  | L      | L  | Н       |
| L  | L      | Н  | Н       |
| L  | Н      | L  | Н       |
| L  | Н      | Н  | Н       |
|    |        |    |         |
| Н  | L      | L  | Н       |
| Н  | L      | Н  | Н       |
| Н  | Н      | L  | Н       |
| Н  | Н      | Н  | L       |

#### NOTES:

H = HIGH voltage level L = LOW voltage level

#### RECOMMENDED OPERATING CONDITIONS

| SYMBOL                          | PARAMETER                                       | CONDITIONS                                 | MIN        | TYP. | MAX             | UNIT |
|---------------------------------|---|--|------------|------|-----------------|------|
| V <sub>CC</sub>                 | DC supply voltage                               | See Note1                                  | 1.0        | 3.3  | 3.6             | V    |
| VI                              | Input voltage                                   |  | 0          | -    | V <sub>CC</sub> | V    |
| Vo                              | Output voltage                                  |  | 0          | -    | V <sub>CC</sub> | V    |
| T <sub>amb</sub>                | Operating ambient temperature range in free air | See DC and AC characteristics              | -40<br>-40 |      | +85<br>+125     | °C   |
|                                 |   | V <sub>CC</sub> = 1.0 V to 2.0 V           | _          | -    | 500             | ns/V |
| t <sub>r</sub> , t <sub>f</sub> | Input rise and fall times                       | V <sub>CC</sub> = 2.0 V to 2.7 V           | _          | _    | 200             | ns/V |
|                                 |   | $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ | _          | -    | 100             | ns/V |

#### NOTE:

<sup>1.</sup> The LV is guaranteed to function down to  $V_{CC}$  = 1.0 V (input levels GND or  $V_{CC}$ ); DC characteristics are guaranteed from  $V_{CC}$  = 1.2 V to  $V_{CC}$  = 3.6 V.

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#### **ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>**

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0 V).

| SYMBOL                                  | PARAMETER  | CONDITIONS  | RATING       | UNIT |
|---|--|---|--------------|------|
| V <sub>CC</sub>                         | DC supply voltage  |   | -0.5 to +4.6 | V    |
| ±I <sub>IK</sub>                        | DC input diode current                                     | $V_{I} < -0.5 \text{ V or } V_{I} > V_{CC} + 0.5 \text{ V}$                       | 20           | mA   |
| ±I <sub>OK</sub>                        | DC output diode current                                    | $V_{O} < -0.5 \text{ V or } V_{O} > V_{CC} + 0.5 \text{ V}$                       | 50           | mA   |
| ±ΙΟ                                     | DC output source or sink current (standard outputs)        | -0.5 V < V <sub>O</sub> < V <sub>CC</sub> + 0.5 V                                 | 25           | mA   |
| ±I <sub>GND</sub> ,<br>±I <sub>CC</sub> | DC $V_{CC}$ or GND current for types with standard outputs |   | 50           | mA   |
| T <sub>stg</sub>                        | Storage temperature range                                  |   | -65 to +150  | °C   |
| P <sub>TOT</sub>                        | Power dissipation per package  – plastic mini-pack (SO)    | for temperature range: -40 °C to +125 °C above +70 °C derate linearly with 8 mW/K | 500          | mW   |

#### NOTES:

#### DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

|                                      |  |   |      |                  | LIMITS |          |           |                     |
|--------------------------------------|--|---|------|------------------|--------|----------|-----------|---------------------|
| SYMBOL                               | PARAMETER  | TEST CONDITIONS   | -40  | °C to +8         | 5 °C   | –40 °C t | o +125 °C | UNIT                |
|                                      |  |   | MIN  | TYP <sup>1</sup> | MAX    | MIN      | MAX       |                     |
|                                      |  | V <sub>CC</sub> = 1.2 V   | 0.9  |                  |        | 0.9      |           |                     |
| $V_{IH}$                             | HIGH level Input voltage                         | V <sub>CC</sub> = 2.0 V   | 1.4  |                  |        | 1.4      |           | V                   |
|                                      | l vallage  | V <sub>CC</sub> = 2.7 V to 3.6 V  | 2.0  |                  |        | 2.0      |           |                     |
|                                      |  | V <sub>CC</sub> = 1.2 V   |      |                  | 0.3    |          | 0.3       |                     |
| $V_{IL}$                             | LOW level Input voltage                          | V <sub>CC</sub> = 2.0 V   |      |                  | 0.6    |          | 0.6       | V                   |
|                                      | l remage   | V <sub>CC</sub> = 2.7 V to 3.6 V  |      |                  | 0.8    |          | 0.8       | 1                   |
|                                      |  | $V_{CC} = 1.2 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 100 \mu\text{A}$ |      | 1.2              |        |          |           |                     |
| .,                                   | HIGH level output                                | $V_{CC} = 2.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 100 \mu\text{A}$ | 1.8  | 2.0              |        | 1.8      |           | $\mid \ \ \ \ \mid$ |
| V <sub>OH</sub> voltage; all outputs | voltage; all outputs                             | $V_{CC} = 2.7 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 100 \mu\text{A}$ | 2.5  | 2.7              |        | 2.5      |           | 1 '                 |
|                                      |  | $V_{CC} = 3.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 100 \mu\text{A}$ | 2.8  | 3.0              |        | 2.8      |           | 1                   |
| V <sub>OH</sub>                      | HIGH level output voltage; STANDARD outputs      | $V_{CC} = 3.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 6 \text{ mA}$    | 2.40 | 2.82             |        | 2.20     |           | V                   |
|                                      |  | $V_{CC} = 1.2 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100  \mu\text{A}$ |      | 0                |        |          |           |                     |
| .,                                   | LOW level output                                 | $V_{CC} = 2.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100  \mu\text{A}$ |      | 0                | 0.2    |          | 0.2       | 1 ,                 |
| V <sub>OL</sub>                      | voltage; all outputs                             | $V_{CC} = 2.7 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100  \mu\text{A}$ |      | 0                | 0.2    |          | 0.2       | \ \                 |
|                                      |  | $V_{CC} = 3.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100  \mu\text{A}$ |      | 0                | 0.2    |          | 0.2       | 1                   |
| V <sub>OL</sub>                      | LOW level output<br>voltage; STANDARD<br>outputs | $V_{CC} = 3.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 6 \text{ mA}$     |      | 0.25             | 0.40   |          | 0.50      | V                   |
| II                                   | Input leakage current                            | $V_{CC} = 3.6 \text{ V}; V_I = V_{CC} \text{ or GND}$                             |      |                  | 1.0    |          | 1.0       | μΑ                  |
| lcc                                  | Quiescent supply current; SSI                    | $V_{CC} = 3.6 \text{ V}; V_I = V_{CC} \text{ or GND}; I_O = 0$                    |      |                  | 20.0   |          | 40        | μА                  |
| Δl <sub>CC</sub>                     | Additional quiescent supply current per input    | $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}; V_{I} = V_{CC} - 0.6 \text{ V}$        |      |                  | 500    |          | 850       | μΑ                  |

#### NOTE:

Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the
device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to
absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>2.</sup> The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>1.</sup> All typical values are measured at  $T_{amb}$  = 25 °C.

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#### **AC CHARACTERISTICS**

GND = 0 V;  $t_r$  =  $t_f$   $\leq$  2.5 ns;  $C_L$  = 50 pF;  $R_L$  = 1  $k\Omega$ 

|         |   |             | WAVEFORM CONDITION  |     | LIMITS           |     |     |                   |    |  |
|---------|---|-------------|---------------------|-----|------------------|-----|-----|-------------------|----|--|
| SYMBOL  | PARAMETER   | WAVEFORM    |                     |     | -40 °C to +85 °C |     |     | -40 °C to +125 °C |    |  |
|         |   |             | V <sub>CC</sub> (V) | MIN | TYP <sup>1</sup> | MAX | MIN | MAX               |    |  |
|         |   |             | 1.2                 |     | 55               |     |     |                   |    |  |
| 1.      | t <sub>PHL/PLH</sub> Propagation delay nA, nB, nC to nY | Figure 1, 2 | Figure 1 2          | 2.0 |                  | 19  | 36  |                   | 44 |  |
| PHL/PLH |   |             | 2.7                 |     | 14               | 26  |     | 33                | ns |  |
|         |   |             | 3.0 to 3.6          |     | 10 <sup>2</sup>  | 21  |     | 26                |    |  |

#### NOTES:

- 1. Unless otherwise stated, all typical values are measured at  $T_{amb}$  = 25 °C. 2. Typical values are measured at  $V_{CC}$  = 3.3 V.

#### **AC WAVEFORMS**

 $V_{\mbox{\scriptsize M}}$  = 1.5 V at  $V_{\mbox{\scriptsize CC}} \geq$  2.7 V;

 $V_{\mbox{\scriptsize M}} = 0.5 \times V_{\mbox{\scriptsize CC}}$  at  $V_{\mbox{\scriptsize CC}} < 2.7 \mbox{\ V};$ 

 $V_{OL}$  and  $V_{OH}$  are the typical output voltage drop that occur with the output load.

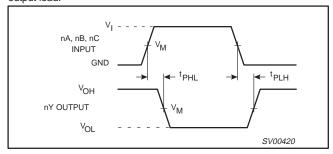


Figure 1. Input (nA, nB, nC) to output (nY) propagation delays.

#### **TEST CIRCUIT**

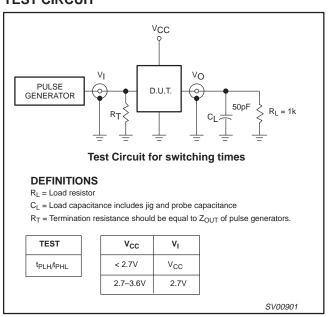


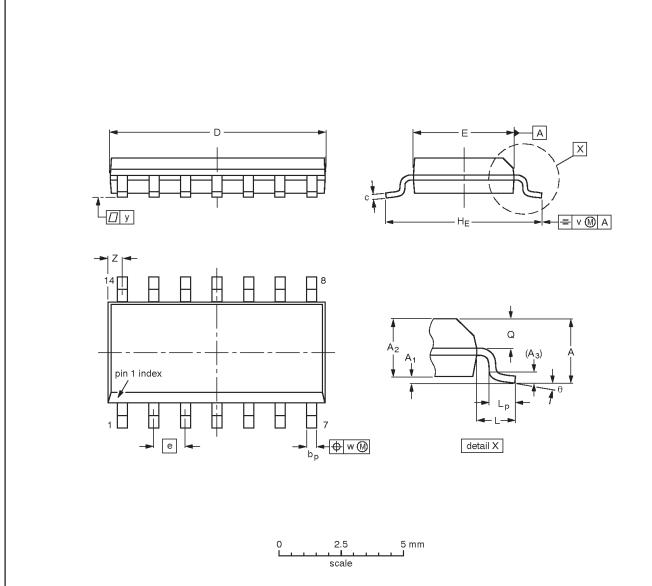
Figure 2. Load circuitry for switching times.

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### SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

|        | •         |                |                |                |              |                  | _                |                  |       |                |       |                |                |      |      |       |                  |    |
|--------|-----------|----------------|----------------|----------------|--------------|------------------|------------------|------------------|-------|----------------|-------|----------------|----------------|------|------|-------|------------------|----|
| UNIT   | A<br>max. | A <sub>1</sub> | A <sub>2</sub> | A <sub>3</sub> | bp           | С                | D <sup>(1)</sup> | E <sup>(1)</sup> | е     | HE             | L     | Lp             | Q              | v    | w    | у     | Z <sup>(1)</sup> | θ  |
| mm     | 1.75      | 0.25<br>0.10   | 1.45<br>1.25   | 0.25           | 0.49<br>0.36 | 0.25<br>0.19     | 8.75<br>8.55     | 4.0<br>3.8       | 1.27  | 6.2<br>5.8     | 1.05  | 1.0<br>0.4     | 0.7<br>0.6     | 0.25 | 0.25 | 0.1   | 0.7<br>0.3       | 8° |
| inches | 0.069     | 0.010<br>0.004 | 0.057<br>0.049 | 0.01           |              | 0.0100<br>0.0075 | 0.35<br>0.34     | 0.16<br>0.15     | 0.050 | 0.244<br>0.228 | 0.041 | 0.039<br>0.016 | 0.028<br>0.024 | 0.01 | 0.01 | 0.004 | 0.028<br>0.012   | 0° |

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

| OUTLINE  |        | REFER  | RENCES | EUROPEAN ISSUE DATE |                                  |  |  |
|----------|--------|--------|--------|---------------------|----------------------------------|--|--|
| VERSION  | IEC    | JEDEC  | EIAJ   | PROJECTION          | ISSUE DATE                       |  |  |
| SOT108-1 | 076E06 | MS-012 |        |                     | <del>-97-05-22</del><br>99-12-27 |  |  |

2003 Mar 04 6

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#### **REVISION HISTORY**

| Rev | Date     | Description  |  |  |  |  |
|-----|----------|--|--|--|--|--|
| _3  | 20030304 | Product data (9397 750 11193). ECN 853-1919 29491 of 07 February 2003.<br>Supersedes data of 1998 Apr 20 (9397 750 04407). |  |  |  |  |
|     |          | Modifications:   |  |  |  |  |
|     |          | Delete DIL, SSOP and TSSOP package ordering and package outlines (discontinued options).                                   |  |  |  |  |
|     |          | Correct power dissipation formula.   |  |  |  |  |
| _2  | 19980420 | Product specification (9397 750 04407). ECN 853-1919 19256 of 20 April 1998. Supersedes data of 1997 Feb 12.               |  |  |  |  |

#### Data sheet status

| Level | Data sheet status [1] | Product<br>status <sup>[2] [3]</sup> | Definitions  |
|-------|-----------------------|--------------------------------------|--|
| I     | Objective data        | Development                          | This data sheet contains data from the objective specification for product development.  Philips Semiconductors reserves the right to change the specification in any manner without notice.   |
| II    | Preliminary data      | Qualification                        | This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.             |
| III   | Product data          | Production                           | This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN). |

<sup>[1]</sup> Please consult the most recently issued data sheet before initiating or completing a design.

#### **Definitions**

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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<sup>[2]</sup> The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

<sup>[3]</sup> For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.